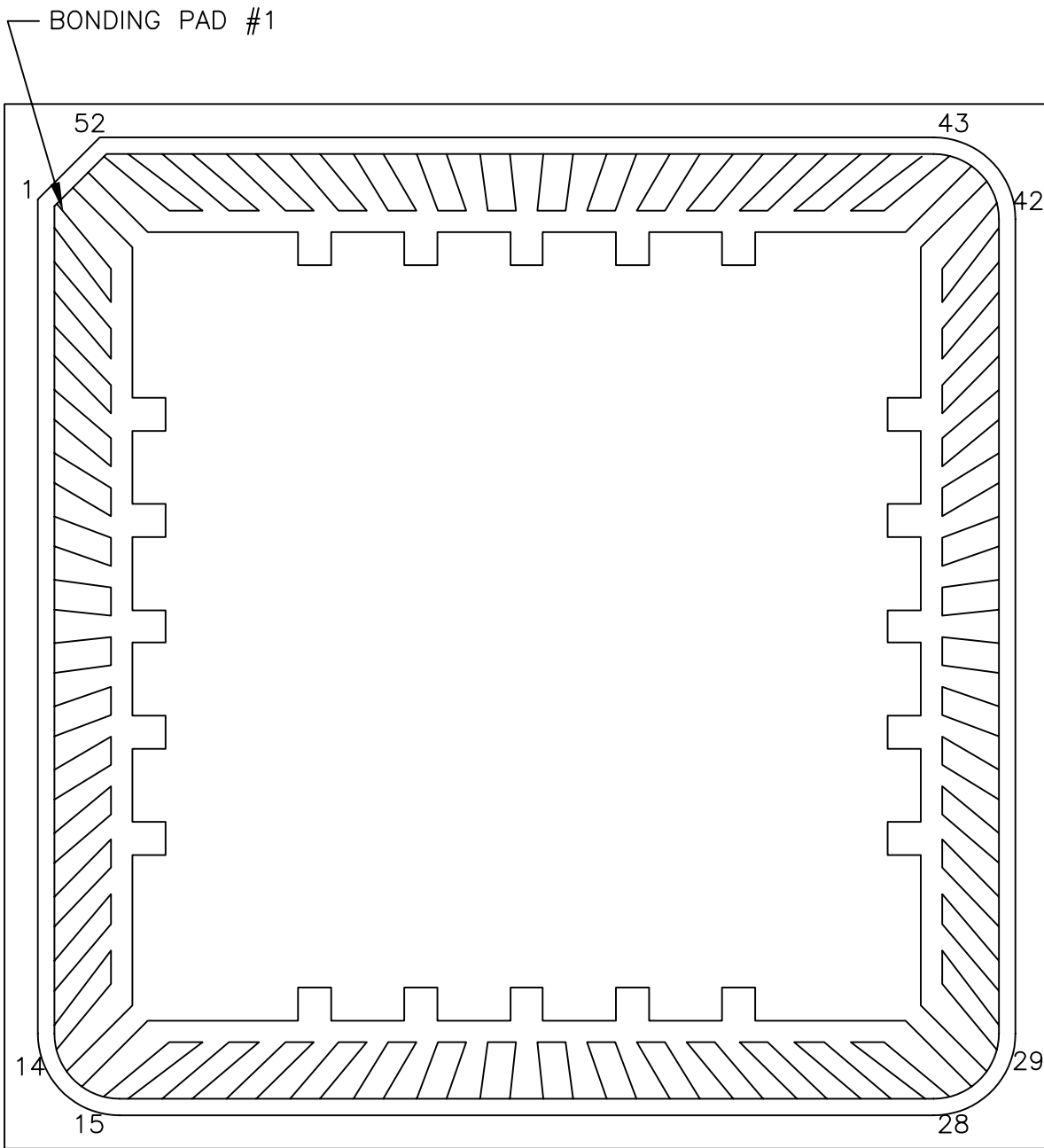


| SEMPAC REVISIONS |          |                    |           |
|------------------|----------|--------------------|-----------|
| ECN NO.          | DATE     | DESCRIPTION        | APPROVED  |
| 10733            | 10/16/06 | PRODUCTION RELEASE | D. MORRIS |
| DRAWN BY         | C CRUZ   | DATE               | 10/16/06  |
|                  |          | APP BP.            | FLASKERUD |
|                  |          | DATE               | 10/16/06  |



|  |                                   |  |  |               |
|--|-----------------------------------|--|--|---------------|
| DEVICE TYPE:   |                                   | <b>SEMPAC, INC.</b><br>Open-Pak™ Technologies<br><a href="http://www.sempac.com">www.sempac.com</a><br>568 E. WEDDELL DRIVE, SUITE 5<br>SUNNYVALE, CALIFORNIA 94089<br>PHONE: (408) 400-9002 FAX: (408) 400-9006 |  |               |
| CUSTOMER: ---  |                                   |  |  | DIE SIZE:     |
| WIRE TYPE/<br>SIZE:  |                                   |  |  | NO. OF WIRES: |
| THIRD ANGLE PROJECTION   | PACKAGE SIZE: 8.00mm X 8.00mm     | 52 LEAD 8mm x 8mm MLP<br>Open-Pak™ BONDING DIAGRAM   |  |               |
| UNLESS OTHERWISE SPECIFIED<br>DIMENSIONS ARE IN MILLIMETER<br>DO NOT SCALE DRAWING | DIE PAD SIZE: 6.04mm X 6.04mm     |  |  |               |
| SEMPAC PART NO.<br>MLP8X8-52-OP-01   |                                   | THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO SEMPAC, INC., AND REPRODUCTION OR ISSUE IN ANY FORM IS NOT PERMITTED WITHOUT AUTHORITY FROM SEMPAC, INC.   |  |               |
| SIZE<br>A  | PART NO.<br>MLP8X8-52-OP-01       | REV<br>1   |  |               |
| SCALE 20X  | CAD FILE MLP8X8-52-OP-01-B-R1.DWG | SHEET 1 OF 1   |  |               |